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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Takashi HIRAGA et al.

ATTN: PCT Branch

Application No.: 09/913,315

Docket No.: 110345

Filed: August 10, 2001

For: MODIFICATION METHOD OF SURFACE LAYER OF MOLDED RESIN
ARTICLE, AND MODIFICATION APPARATUS OF SURFACE LAYER OF
MOLDED RESIN ARTICLE

**NOTIFICATION OF ACCEPTANCE AND
FILING RECEIPT STATUS REQUEST**

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231


Sir:

The above-captioned patent application was filed on August 10, 2001. All 35 U.S.C 371 requirements were also satisfied on August 10, 2001. A copy of the postcard receipt is attached hereto.

The original Notification of Acceptance and Filing Receipt have not yet been received. It is respectfully requested that the original Notification of Acceptance and Filing Receipt be immediately forwarded to the attorneys of record at the address set forth below.

If there are any questions regarding this matter, please contact the undersigned at the telephone number set forth below.

Respectfully submitted,


James A. Oliff
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JAO:JSA/zmc

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PTO RECEIPT FOR FILING OF PA

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The following papers have been filed: **533 Rec'd PCT/PTO 10 AUG 2001**

PCT t, ck 121728 \$1514, PRELIM AM, ANXIPER, REQ, 102pp spec/45clms/abs, 12pp drwns
(1-12), DEC, assign t, ck 121729 \$40, ASSIGN, IDS pto 1449 srch rpt
Srefs/1abs/1conexp/2partrans

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Serial No.: US National Stage of PCT/JP00/02098

Atty. File No.: 110345

Title (New Cases): MODIFICATION METHOD OF SURFACE LAYER OF MOLDED
RESIN ARTICLE, AND MODIFICATION APPARATUS OF SURFACE
LAYER OF MOLDED RESIN ARTICLE

Sender's Initials: JAO/zmc

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